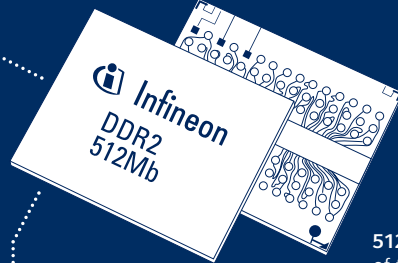


## Memory Products

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**512 Megabit DDR2 SDRAM,** memory component ::: one of the many products in the Memory Products portfolio

## Product innovations

- ::: Next technology generation presented: first functional samples in 90-nanometer technology are available. The 90-nanometer volume production will begin next year with 512 megabit DDR memory chips.
- ::: Standard DRAM memory with DDR2 interface to come: market launch was in July 2004 for PCs and servers. Next year DDR2 will replace the current DDR generation as a main volume product.
- ::: New memory modules developed: with the micro DIMM, an even smaller memory module for sub-notebooks has been presented. Together with the Wireline Communications business group, a buffer memory for high-speed data transport has been developed, which is to be used in the next generation server modules: the so-called fully buffered DIMMs.
- ::: Specialty memories for 3D graphics cards available: the 500 megahertz GDDR3 graphics memories support highly sophisticated graphics applications.
- ::: DRAMs optimized to run on low power consumption: the 256 megabit Mobile-RAM is now available for 1.8 volt supply voltage and is targeted at smart phones. The 32 megabit CellularRAM replaces expensive SRAMs in mobile phones.
- ::: Introduction of first flash components: at the beginning of 2004, Infineon Technologies Flash, the joint venture with Saifun, Israel, stepped into the market of flash memories with a 512 megabit chip. The flash components can be integrated into USB sticks and flash cards of format secure digital (SD) cards as well as the MultiMediaCard.

